

Appl. No. : 10/007,304  
Filed : December 5, 2001

50. (Amended) A diffusion barrier for a copper interconnect comprising:  
a first layer of metal nitride;  
a layer of reactive metal over the first layer of metal nitride; and  
a second layer of metal nitride over the layer of reactive metal, wherein the grain boundaries of the first and second metal nitride layers are stuffed with a compound of a metal different from the metal in the nitride layers.
51. (Amended) The diffusion barrier of Claim 50, wherein the compound of a metal different from the metal in the nitride layers is selected from the group consisting of an oxide of the reactive metal and a nitride of the reactive metal.

#### REMARKS

Prior to examination, Applicants have amended the claims to correct obvious errors and to match follow-on recitations with their antecedents. Applicants submit that the amendments introduce no new matter and are fully supported by the application as filed.

A marked-up version of the amendments is appended on separate pages entitled VERSION OF AMENDMENTS SHOWING CHANGES MADE, wherein additions are showing in double-underlining and deletions are shown in ~~strike-through text~~. Also appended for the Examiner's convenience is a clean version of the claims after entry of the amendments.

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: December 20, 2002

By: Adeel S. Akhtar

Adeel S. Akhtar  
Registration No. 41,394  
Attorney of Record  
Customer No. 20,995  
(415) 954-4114